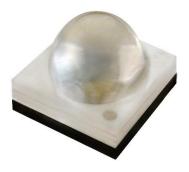


www.prolightopto.com





ProLight PB2D-3JLA-Gx 3W UV Power LED Technical Datasheet Version: 2.2

# **ProLight Opto PB2D Series**

# Features

- · Best thermal material solution of the world
- · Best Moisture Sensitivity: JEDEC Level 1
- · RoHS compliant
- · Quartz Glass Lens
- $\cdot$  View angle 30°

# **Main Applications**

- $\cdot$  UV gluing, UV curing, UV marking
- $\cdot$  UV drying of printing inks and lacquers
- $\cdot$  Currency inspection
- · Forensic analysis urine, protein stains
- $\cdot$  Leak detection using fluorescent dyes
- $\cdot$  Detects fluorescing minerals and gems

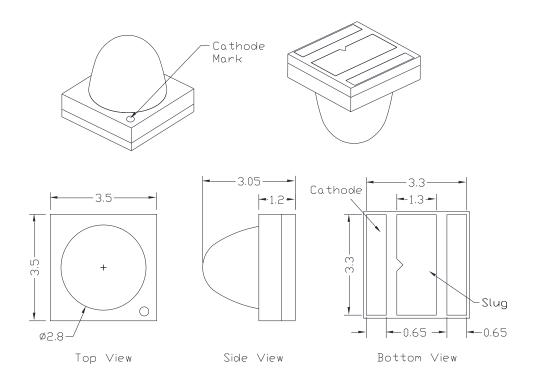
# Introduction

•ProLight PB2D-3JLA-viewing angle 30° Quartz Package, is one of the smallest high power LED footprint available by ProLight Opto, has offered extended solid-state lighting design possibilities. ProLight PB2D-3JLA-viewing angle 30° is designed with ProLight own Patents and using copper leadframe, the best thermal material of the world.

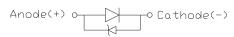
•PB2D-3JLA-viewing angle 30° qualifies as the JEDEC Level 1 MSL sensitivity level and suitable for SMD process, Pb\_free reflow soldering capability, and full compliance with EU Reduction of Hazardous Substances (RoHS) legislation.



# **Emitter Mechanical Dimensions**



Circuit Diagram



Notes:

- 1. The cathode side of the device is denoted by the chamfer on the part body.
- 2. Electrical insulation between the case and the board is required. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. Unless otherwise indicated, tolerances are  $\pm$  0.10mm.
- 6. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

\*The appearance and specifications of the product may be modified for improvement without notice.



# Flux Characteristics, $T_j = 25^{\circ}C$

Radiation Pa		Part Number	Radiometric Power (mW)			
Pattern	Color		@700mA		Refer @500mA	
Fallen		Emitter	Minimum	Typical	Typical	
	UV-S	PB2D-3JLA-GS	830	1085	770	
Lambertian	UV-M	PB2D-3JLA-GM	910	1230	870	
Lampentan	UV	PB2D-3JLA-G	1000	1200	860	
	UV-L	PB2D-3JLA-GL	1000	1280	900	

• ProLight maintains a tolerance of ± 10% on flux and power measurements.

• Please do not drive at rated current more than 1 second without proper heat sink.

# Electrical Characteristics, $T_J = 25^{\circ}C$

		Forward \ @700mA	/oltage V <sub>F</sub> (\	/) Refer @500mA	Thermal Resistance
Color	Min.	Тур.	Max.	Тур.	Junction to Slug (°C/ W)
UV-S	3.20	3.50	4.00	3.65	8
UV-M	2.80	3.45	3.80	-	8
UV	2.80	3.45	3.80	-	8
UV-L	2.80	3.45	3.80	-	8

• ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

# Optical Characteristics at 700mA, $T_J = 25^{\circ}C$

Radiation	Color	Pe	ak Wavelength	λp	Total included Angle (degrees)	Viewing Angle (degrees)
Pattern	COIOI	Min.	Тур.	Max.	θ <sub>0.90V</sub>	<b>2 θ</b> <sub>1/2</sub>
	UV-S	365 nm	367.5 nm	370 nm	60	30
Lambertian	UV-M	380 nm	385 nm	390 nm	60	30
Lampenian	UV	390 nm	395 nm	400 nm	60	30
	UV-L	400 nm	405 nm	410 nm	60	30

• ProLight maintains a tolerance of ± 3nm for dominant wavelength measurements.



# **Absolute Maximum Ratings**

Parameter	UV-S/UV-M/UV/UV-L	
DC Forward Current (mA)	1000	
Peak Pulsed Forward Current (mA)	1100 (less than 1/10 duty cycle@1KHz)	
ESD Sensitivity	±4000V	
(HBM per MIL-STD-883E Method 3015.7)		
LED Junction Temperature	125°C	
Operating Board Temperature	-40°C - 85°C	
at Maximum DC Forward Current		
Storage Temperature	-40°C - 100°C	
Soldering Temperature	JEDEC 020c 260°C	
Allowable Reflow Cycles	3	
Reverse Voltage	Not designed to be driven in reverse bias	

#### **Radiometric Power Bin Structure at 700mA**

Color	Bin Code	Minimum Radiometric Power (mW)	Maximum Radiometric Power (mW)	Available Color Bins
	U1	830	910	All
UV-S	U2	910	1000	All
00-5	V1	1000	1100	All
	V2	1100	1210	All
	U2	910	1000	All
	V1	1000	1100	All
UV-M	V2	1100	1210	All
0 v - ivi	W1	1210	1330	All
	W2	1330	1460	All
	X1	1460	1610	[1]
	V1	1000	1100	All
	V2	1100	1210	All
UV	W1	1210	1330	All
	W2	1330	1460	All
	V1	1000	1100	All
	V2	1100	1210	All
UV-L	W1	1210	1330	All
	W2	1330	1460	All

 $\bullet$  ProLight maintains a tolerance of  $\pm$  10% on flux and power measurements.

• The flux bin of the product may be modified for improvement without notice.

• <sup>[1]</sup> The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.



# **Peak Wavelength Bin Structure**

Color	Bin Code	Minimum Peak Wavelength (nm)	Maximum Peak Wavelength (nm)
UV-S	] 2	365	370
UV-M	B	380	385
	A	385	390
UV	1	390	395
	2	395	400
UV-L	3	400	405
	4	405	410

• ProLight maintains a tolerance of ± 3nm for peak wavelength measurements.

### **Forward Voltage Bin Structure**

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
	D	3.2	3.4
UV-S	E	3.4	3.6
00-3	F	3.6	3.8
	G	3.8	4.0
	В	2.8	3.0
	С	3.0	3.2
UV-M	D	3.2	3.4
	E	3.4	3.6
	F	3.6	3.8
	В	2.8	3.0
	С	3.0	3.2
UV	D	3.2	3.4
	E	3.4	3.6
	F	3.6	3.8
	В	2.8	3.0
	С	3.0	3.2
UV-L	D	3.2	3.4
	E	3.4	3.6
	F	3.6	3.8

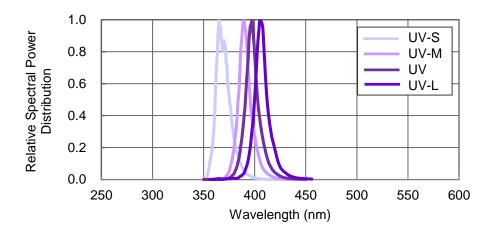
• ProLight maintains a tolerance of  $\pm$  0.1V for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.



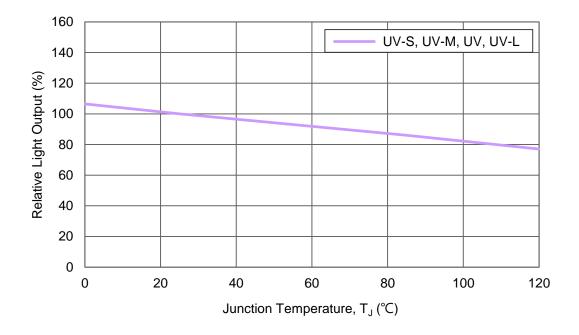
# Color Spectrum, T<sub>J</sub> = 25°C

1. UV-S, UV-M, UV, UV-L



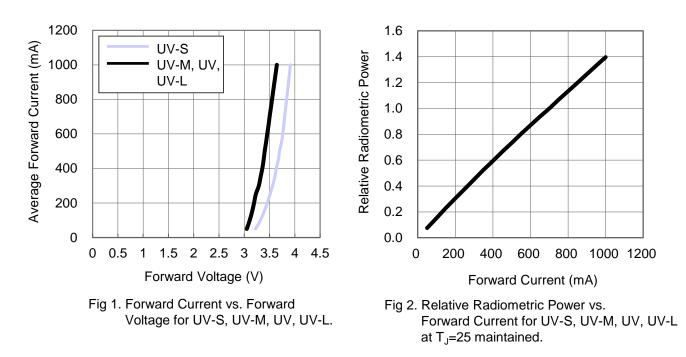
# **Light Output Characteristics**

Relative Light Output vs. Junction Temperature at 700mA



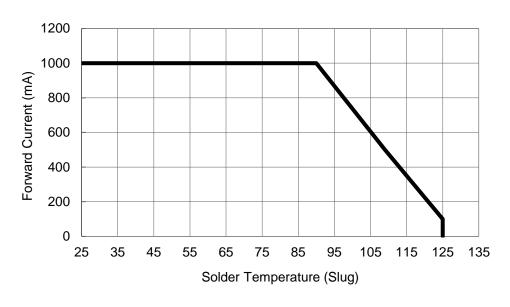


# Forward Current Characteristics, T<sub>1</sub> = 25°C



#### Solder Temperature (Slug) vs. Maximum Forward Current

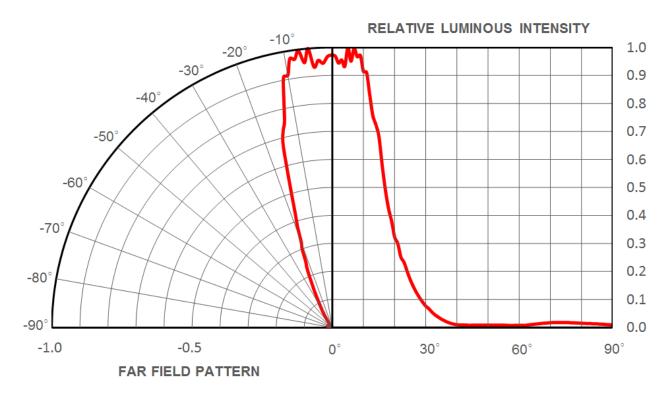
1. UV-S, UV-M, UV, UV-L (T<sub>JMAX</sub> = 125°C)



2024/03 | DS-1107



# **Typical Representative Spatial Radiation Pattern**





# **Moisture Sensitivity Level - JEDEC Level 1**

				Soak Req	uirements	
Level	Floo	r Life	Stan	dard	Accelerated	Environment
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

				Soak Req	uirements	
Level	Level Floor Life		Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA
2a	4 weeks	≤30°C / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	≤30°C / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	≤30°C / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	≤30°C / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	≤30°C / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA



# **Qualification Reliability Testing**

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I <sub>F</sub> = max DC (Note 1)	1000 hours	Note 2
High Temperature Storage Life (HTSL)	100°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 100°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

1. Depending on the maximum derating curve.

2. Criteria for judging failure

ltem	Test Condition	Criteria for Judgement		
nem	Test Condition	Min.	Max.	
Forward Voltage (V <sub>F</sub> )	I <sub>F</sub> = max DC		Initial Level x 1.1	
Luminous Flux or Radiometric Power ( $\Phi_V$ )	I <sub>F</sub> = max DC	Initial Level x 0.7		

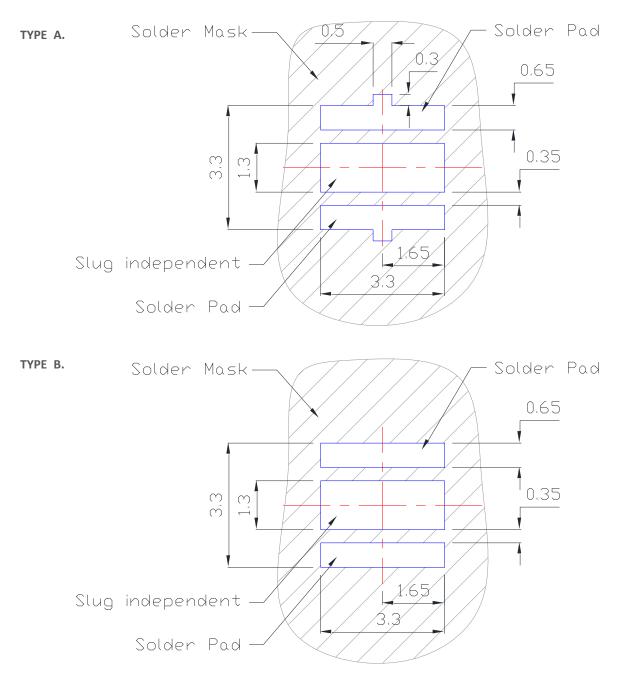
\* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.



# **Recommended Solder Pad Design**

#### **Standard Emitter**

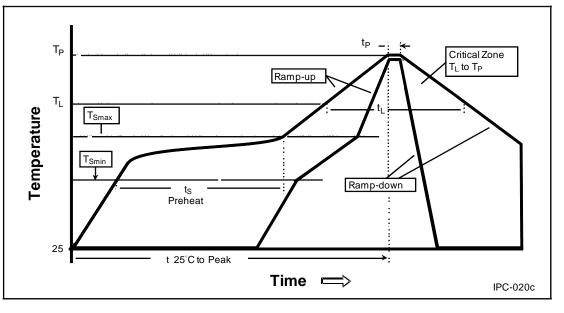


- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.



# **Reflow Soldering Condition**

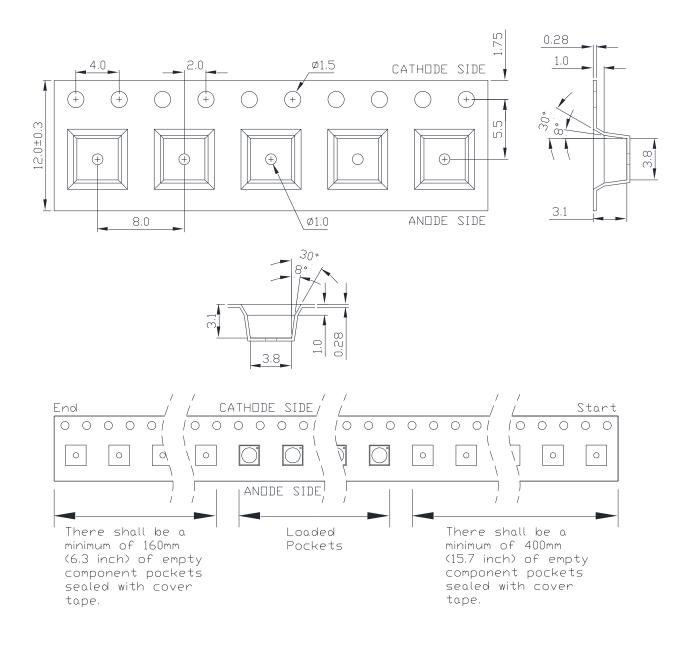
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate	3°C / second max.	3°C / second max.
(T <sub>Smax</sub> to T <sub>P</sub> )	5 C/ second max.	3 C7 second max.
Preheat		
– Temperature Min (T <sub>smin</sub> )	100°C	150°C
– Temperature Max (T <sub>Smax</sub> )	150°C	200°C
– Time (t <sub>smin</sub> to t <sub>smax</sub> )	60-120 seconds	60-180 seconds
Time maintained above:		
– Temperature (T <sub>L</sub> )	183°C	217°C
– Time (t <sub>i</sub> )	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T <sub>P</sub> )	240°C	260°C
Time Within 5°C of Actual Peak	10-30 seconds	20-40 seconds
Temperature (t <sub>P</sub> )	10-30 Seconds	20-40 Seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.



# **Emitter Reel Packaging**

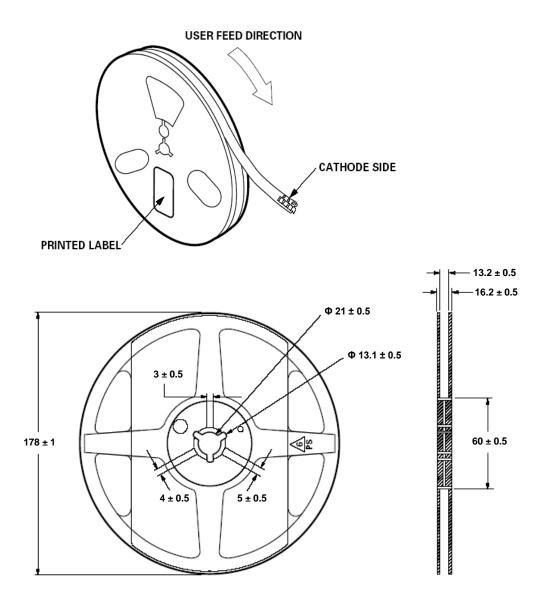


Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are  $\pm\,0.10\text{mm}.$



# **Emitter Reel Packaging**



Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 250, 500 pieces per reel.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.



# **Precaution for Use**

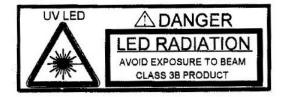
Storage

Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30 °C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

- LEDs are ESD (electrostatic discharge) sensitive; static electricity and surge voltages seriously damage UV LEDs and can result in product failure
  - (1) Ensure that tools, jigs and machines being used are properly grounded
  - (2) LED mounting equipment should include protection against voltage surge
  - (3) Use proper ESD protection, including grounded wrist straps, ESD footwear and clothes
- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/

# **Eye Safety Guidelines**

- During operation, the LED emits high intensity ultraviolet (UV) light, which is harmful to skin and eyes. UV light is hazardous to skin and may cause cancer. Avoid exposure to UV light when LED is operational. Precautions must be taken to avoid looking directly at the UV light without the use of UV light protective glasses. Do not look directly at the front of the LED or at the LED's lens when LED is operational.
- Attach warning labels on products/systems that use UV LEDs.





# **Use Handling of Quartz Lens LEDs**

Notes for handling of quartz lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the quartz lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the quartz lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the quartz lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the quartz lens must be prevented.
- Please do not mold over the quartz lens with another resin. (epoxy, urethane, etc)





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